

1. General description

Planar passivated four quadrant triac in a SOT78(TO-220AB) plastic package intended for use in bidirectional switching and phase control applications.

2. Features and benefits

- High blocking voltage capability
- Less sensitive gate for improved noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants

3. Applications

- General purpose motor control
- General purpose switching

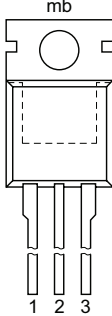
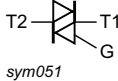
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
Absolute maximum rating						
V_{DRM}	repetitive peak off-state voltage		800			V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 102\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3	8			A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(initial)} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig. 4 ; Fig. 5	65			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G+; $T_j = 25\text{ °C}$; Fig. 7	-	5	35	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G-; $T_j = 25\text{ °C}$; Fig. 7	-	8	35	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G-; $T_j = 25\text{ °C}$; Fig. 7	-	11	35	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G+; $T_j = 25\text{ °C}$; Fig. 7	-	30	70	mA

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BT137-800	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

7. Marking

Table 4. Marking codes

Type number	Marking codes
BT137-800	BT137-800

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 102\text{ °C}$; Fig 1 ; Fig 2 ; Fig 3	8	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig 4 ; Fig 5	65	A
		full sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 16.7\text{ ms}$	71	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN	21	A ² s
di_T/dt	rate of rise of on-state current	$I_G = 70\text{ mA}$; T2+ G+	50	A/ μ s
		$I_G = 70\text{ mA}$; T2+ G-	50	A/ μ s
		$I_G = 70\text{ mA}$; T2- G-	50	A/ μ s
		$I_G = 140\text{ mA}$; T2- G+	10	A/ μ s
I_{GM}	peak gate current		2	A
P_{GM}	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T_{stg}	storage temperature		-40 to 150	°C
T_j	junction temperature		125	°C

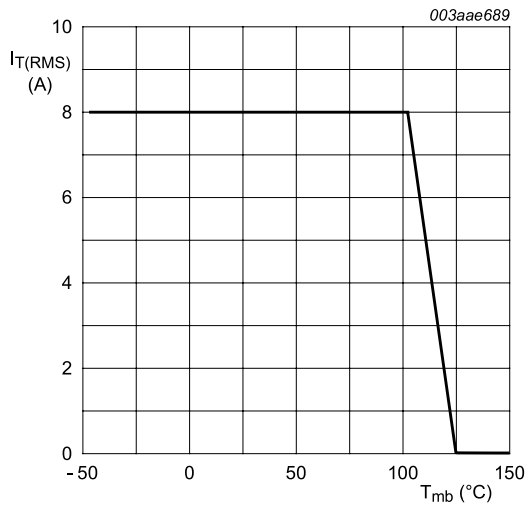
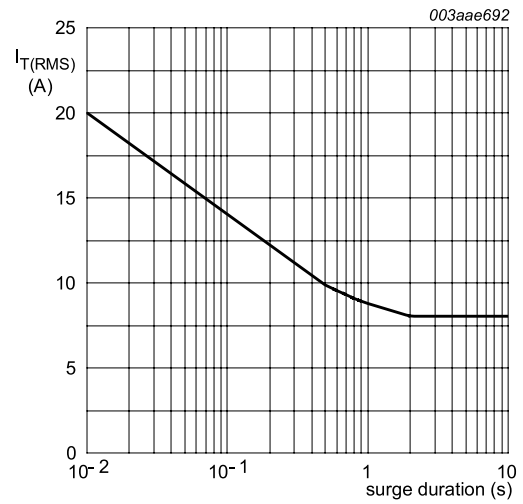
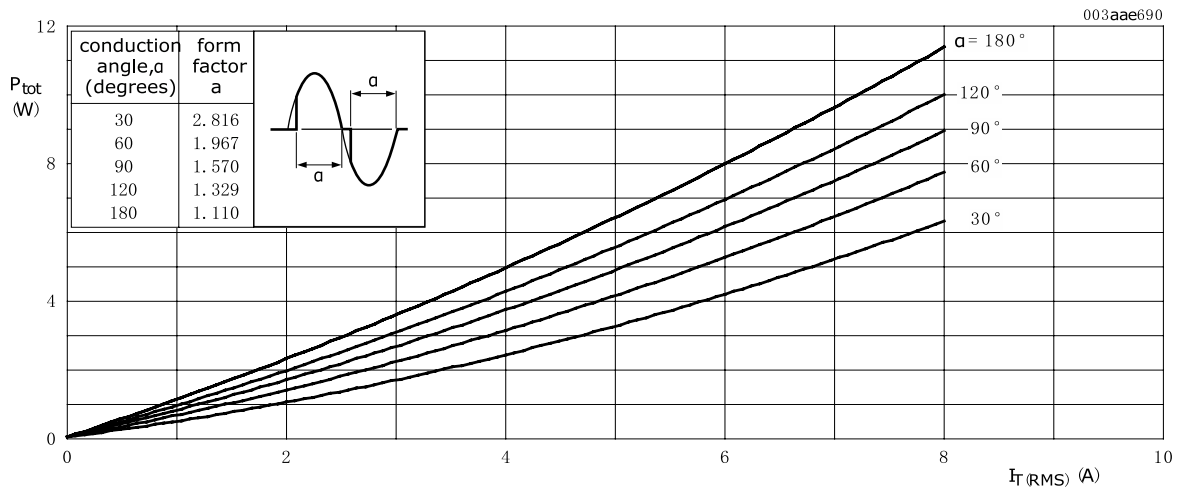


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

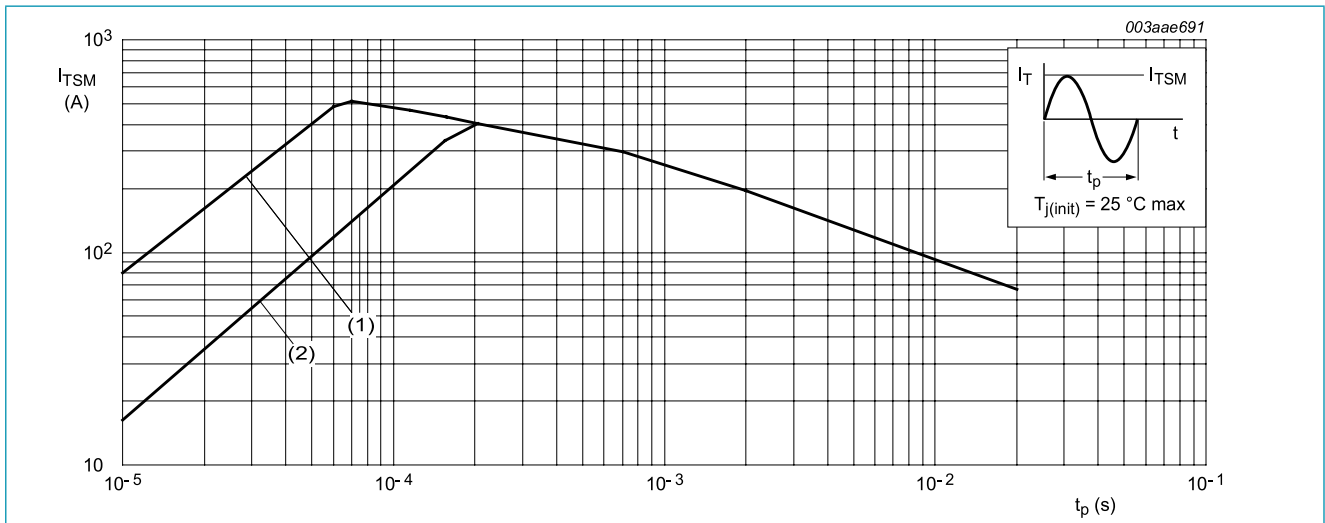


f = 50 Hz; $T_{mb} \leq 102^\circ\text{C}$
 Fig. 2. RMS on-state current as a function of surge duration; maximum values



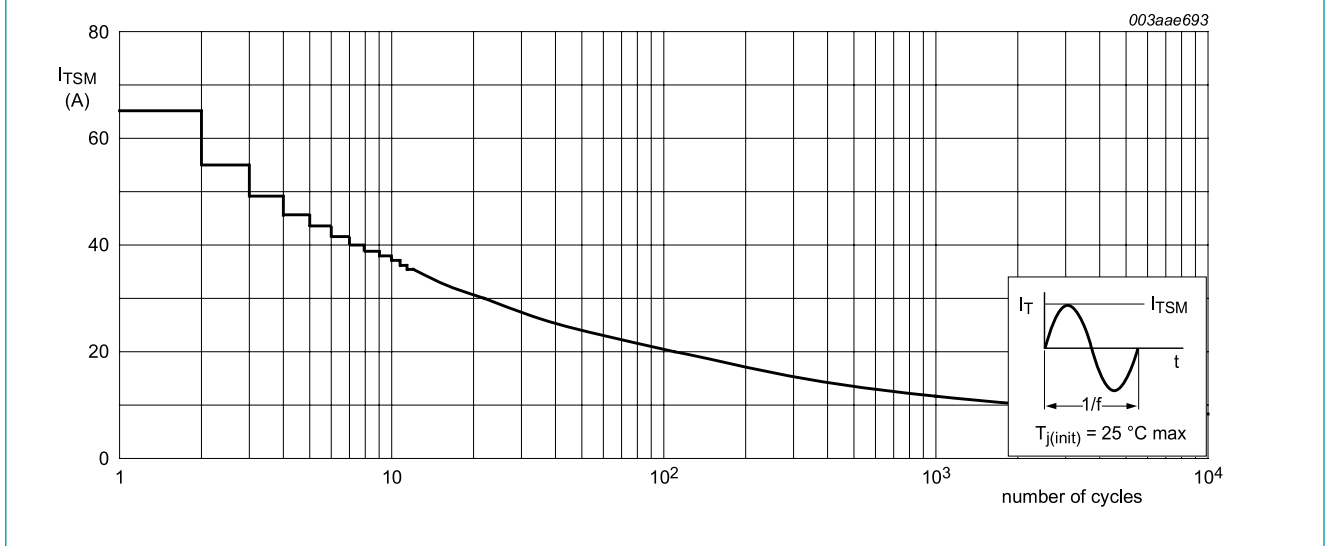
α = conduction angle
 a = form factor = $I_{T(RMS)} / I_{T(AV)}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



$t_p \leq 20\text{ ms}$
 (1) dI_T/dt limit
 (2) T2- G+ quadrant limit

Fig. 4. Non-repetitive peak on-state current as a function of pulse width; maximum values



$f = 50\text{ Hz}$

Fig. 5. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; Fig 6	-	-	2	K/W
		half cycle; Fig 6	-	-	2.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W

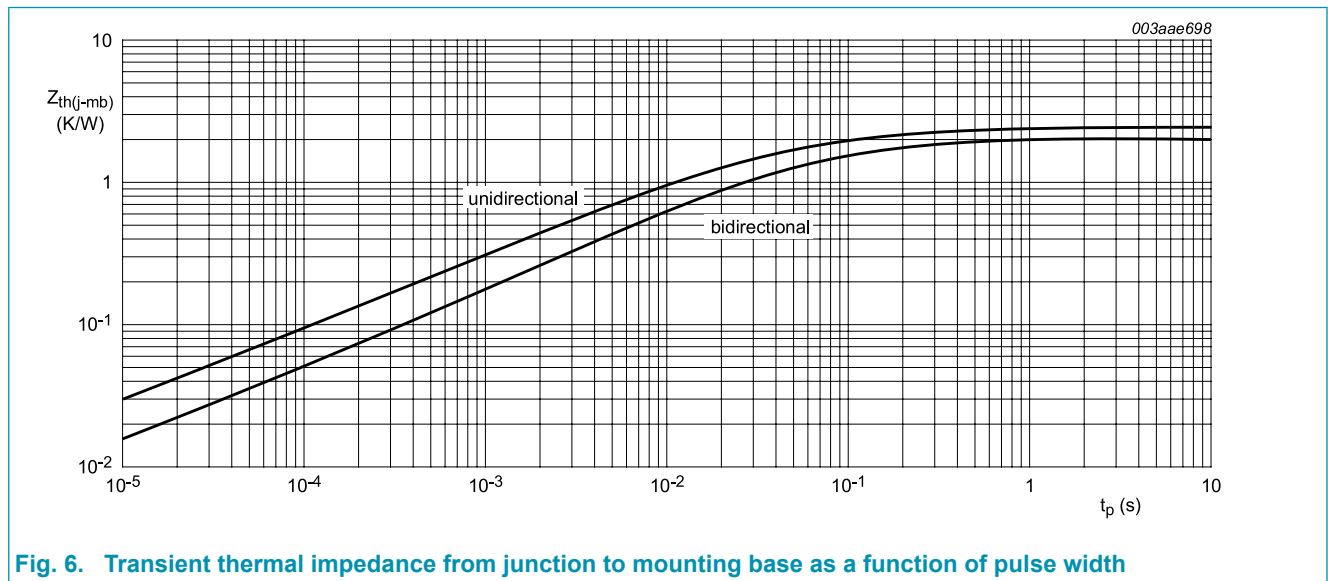
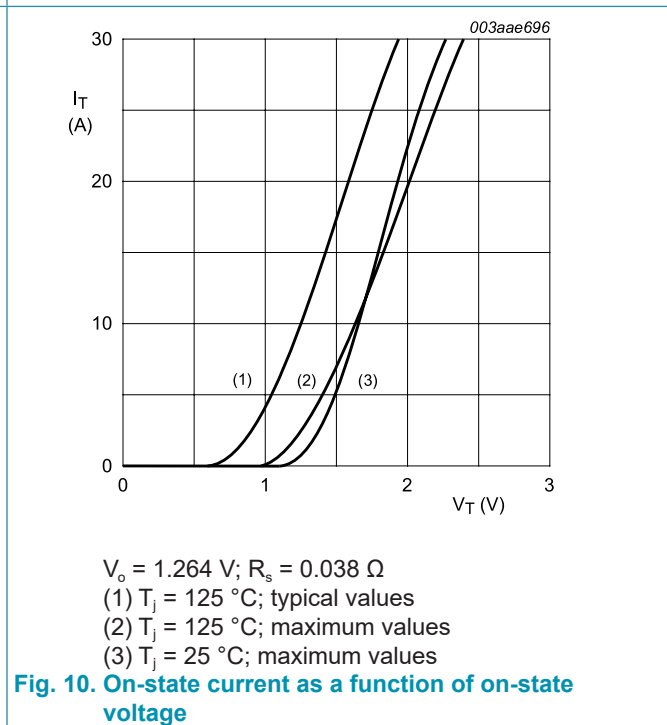
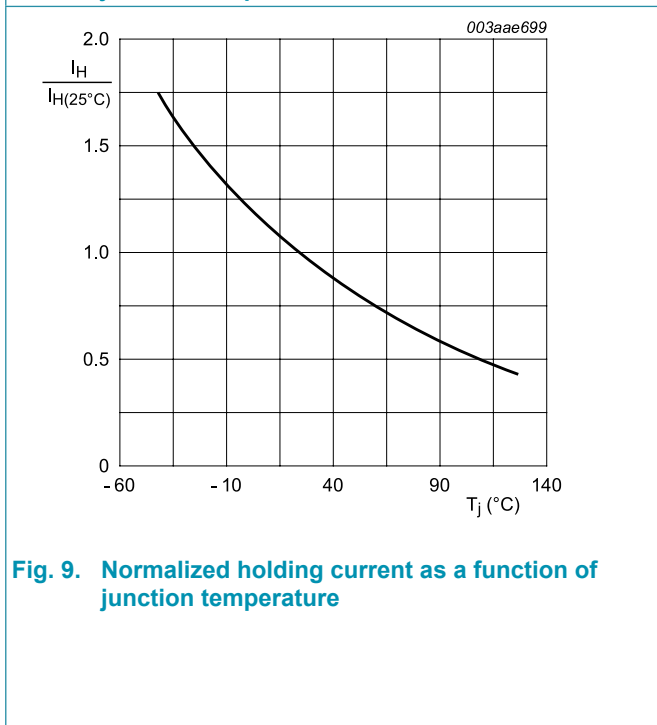
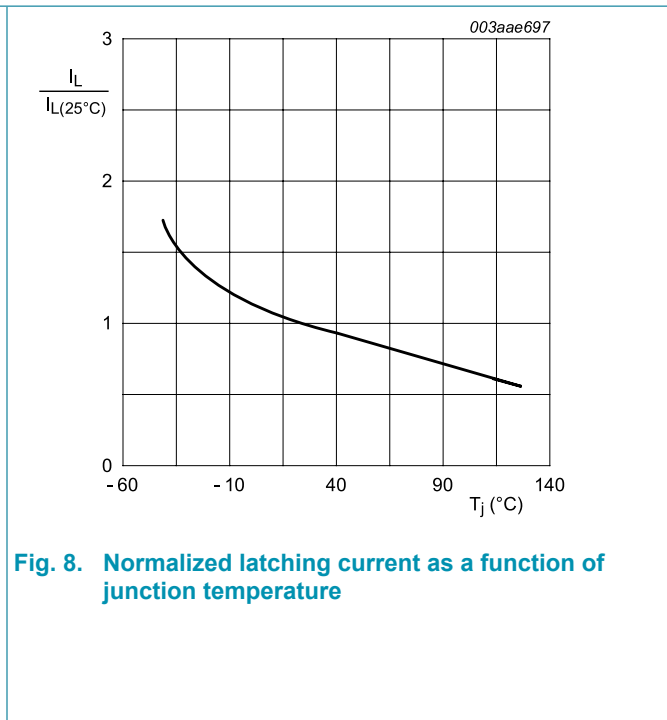
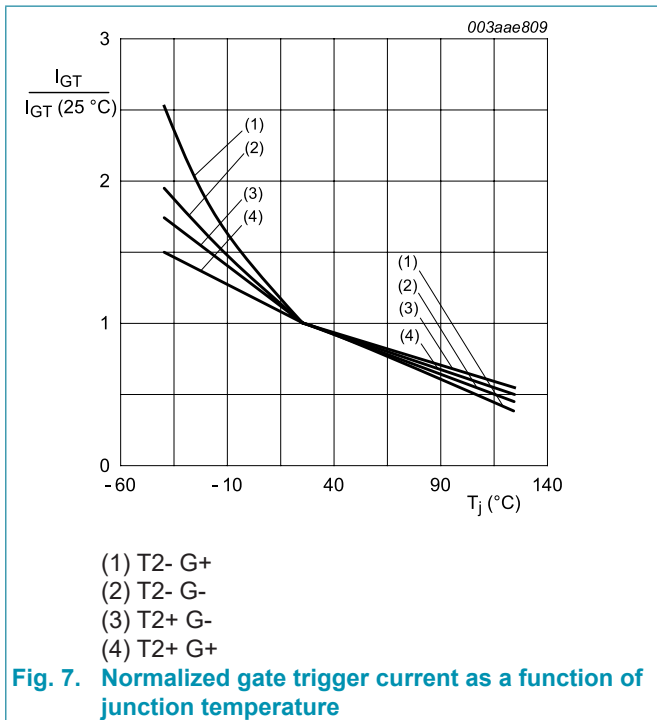


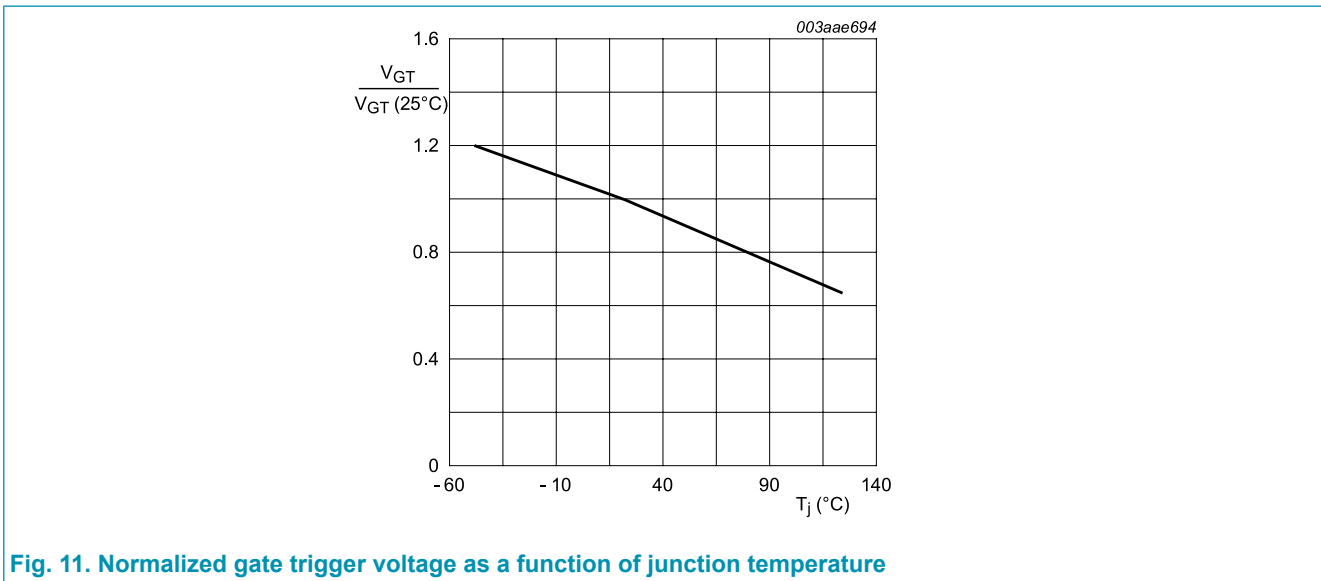
Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse width

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G+;$ $T_J = 25\text{ }^\circ\text{C};$ Fig. 7	-	5	35	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2+ G-;$ $T_J = 25\text{ }^\circ\text{C};$ Fig. 7	-	8	35	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G-;$ $T_J = 25\text{ }^\circ\text{C};$ Fig. 7	-	11	35	mA
		$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_2- G+;$ $T_J = 25\text{ }^\circ\text{C};$ Fig. 7	-	30	70	mA
I_L	latching current	$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2+ G+;$ $T_J = 25\text{ }^\circ\text{C};$ Fig. 8	-	7	30	mA
		$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2+ G-;$ $T_J = 25\text{ }^\circ\text{C};$ Fig. 8	-	16	45	mA
		$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2- G-;$ $T_J = 25\text{ }^\circ\text{C};$ Fig. 8	-	5	30	mA
		$V_D = 12\text{ V}; I_G = 0.1\text{ A}; T_2- G+;$ $T_J = 25\text{ }^\circ\text{C};$ Fig. 8	-	7	45	mA
I_H	holding current	$V_D = 12\text{ V}; T_J = 25\text{ }^\circ\text{C};$ Fig. 9	-	5	20	mA
V_T	on-state voltage	$I_T = 10\text{ A}; T_J = 25\text{ }^\circ\text{C};$ Fig. 10	-	1.3	1.65	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_J = 25\text{ }^\circ\text{C};$ Fig. 11	-	0.7	1	V
		$V_D = 400\text{ V}; I_T = 0.1\text{ A}; T_J = 125\text{ }^\circ\text{C};$ Fig. 11	0.25	0.4	-	V
I_D	off-state current	$V_D = 600\text{ V}; T_J = 125\text{ }^\circ\text{C}$	-	0.1	0.5	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}; T_J = 125\text{ }^\circ\text{C}; (V_{DM} = 67\%$ of $V_{DRM});$ exponential waveform; gate open circuit	100	250	-	V/ μs
dV_{com}/dt	rate of change of commutating voltage	$V_D = 400\text{ V}; T_J = 95\text{ }^\circ\text{C}; dI_{com}/dt = 3.6\text{ A/}$ ms; $I_T = 8\text{ A};$ gate open circuit	-	20	-	V/ μs
t_{gt}	gate-controlled turn-on time	$I_{TM} = 12\text{ A}; V_D = 800\text{ V}; I_G = 0.1\text{ A}; dI_G/$ dt = 5 A/ μs	-	2	-	μs

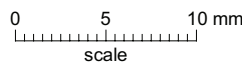




11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁ (2)	b ₂ (2)	c	D	D ₁	E	e	L	L ₁ (1)	L ₂ (1) max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

Notes

- Lead shoulder designs may vary.
- Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT78		3-lead TO-220AB	SC-46		08-04-23 08-06-13

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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